

hyperSPARC™ Dual-CPU Module/Power Module

Features

- Based on ROSS' fourth-generation hyperSPARC™ processor
 - Each module consists of two complete SPARC CPUs
 - Each processor includes
 - RT620C Central Processing Unit (CPU)
 - RT626 Cache Controller, Memory Management, and Tag Unit (CMTU)
 - Four (512-Kbyte) or eight (1-Mbyte) RT628 Cache Data Units (CDUs)
 - Intra-Module Bus incorporates low voltage logic to reduce power and increase speed
 - Dual-level caches
 - Full multiprocessing implementation
 - Hardware support for symmetric, shared-memory multiprocessing
 - Level 2 MBus support for cache coherency
 - SPARC compliant
 - SPARC Instruction Set Architecture (ISA) Version 8 compliant
 - Conforms to SPARC Reference MMU Architecture
 - Conforms to SPARC Level 2 MBus Module Specification (Revision 1.2)
 - Dual-clock architecture
 - CPU scaleable up to 142 MHz
 - MBus scaleable up to 66 MHz
 - Each hyperSPARC processor features
 - Superscalar SPARC CPU with integrated floating point unit and 8-Kbyte instruction cache
 - Zero-wait-state, 512-Kbyte or 1-Mbyte 2nd-level cache
 - Demand-paged virtual memory management
 - Module design
 - CPU Module fits in MBus-standard form factor: 3.30" (8.34 cm) x 5.78" (14.67 cm)
 - Power Module attaches to the rear of the CPU module through a standard 25-pin D shell connector
 - Provides CPU upgrade path at module level
 - Advanced packaging technology for a compact design
 - High performance *
 - 174 SPECint92 (per CPU)
 - 212 SPECfp92 (per CPU)
- * in a 50MHz MBus system

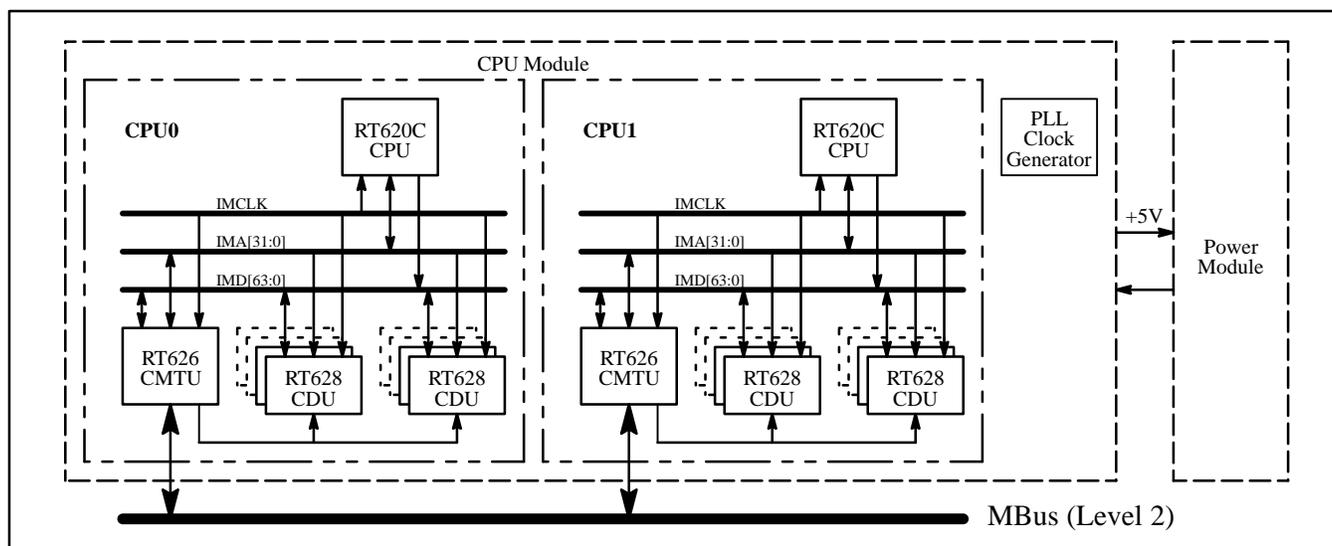


Figure 1. Logic Block Diagram

Selection Guide

Part Number: RT6226N*	-142/1024
CPU Operating Frequency (MHz)	142
Typical Power Consumption (w)**	74
Second-level Cache Size (per CPU)	1M
SPECint92 / SPECfp92	174 / 212
SPECrateint92 / SPECratefp92 (dual processor)	7684 / 9163
SPECrateint92 / SPECratefp92 (quad processor)	

*See Appendix C for hyperSPARC ordering information

** Commercial

Functional Description

The RT6226N hyperSPARC Module consists of a dual CPU module (RT6226N1) and a power module (RT6226N2). The CPU module is a complete dual-SPARC CPU, including on-board primary and secondary cache memories. It is packaged as a compact PCB and interfaces to the remainder of the system via a SPARC-standard MBus connector. Each of the two CPUs on the RT6226N1 consists of a high-speed superscalar, highly pipelined processor with dual integer ALUs and an on-chip floating-point unit (RT620C), a Cache Controller, Memory Management, and Tag Unit (RT626), and four (512-Kbyte) or eight (1-Mbyte) RT628 Cache Data Units. The RT6226N1 fits within the clearance envelope for MBus modules per the SPARC MBus Specification. The RT6226N2 power module provides the low voltage needed by the CPU module from the +5V MBus source. It interfaces to the CPU module through a standard DB-25 connector. It is housed in an enclosure which mounts remotely from the CPU module.

The RT6226N1 interfaces to the rest of the system via the SPARC MBus and conforms to the SPARC Reference MMU. This standardization allows the RT6226N1 to be interchangeable with other SPARC MBus-based CPU modules without having to modify any portion of the memory system or I/O. This CPU "building block" strategy not only decreases the

user's time to market, but provides a mechanism for upgrading in the field.

Component Overview

Superscalar SPARC Processor (RT620C)

The RT620C Central Processing Unit is the heart of ROSS' fourth-generation of microprocessor. The RT620C CPU architecture employs two advanced concepts for increasing computer system performance: superscalability and superpipelining.

The RT620C is a high performance full-custom CMOS implementation of integrated SPARC integer and floating-point logic, with an on-chip cache for instructions.

Advanced architecture and manufacturing technologies give the RT620C ultra high performance without requiring software recompilation. *Figure 2* is a logic block diagram of the RT620C.

IDP. The Integer Data Path comprises several units. Two independent Arithmetic and Logic Units (ALUs) handle integer arithmetic, logical, and shift instructions. The Load/Store Unit (LSU) handles instructions that load and store data between memory and registers which includes the loading and storing of both integer and floating-point data. The Special

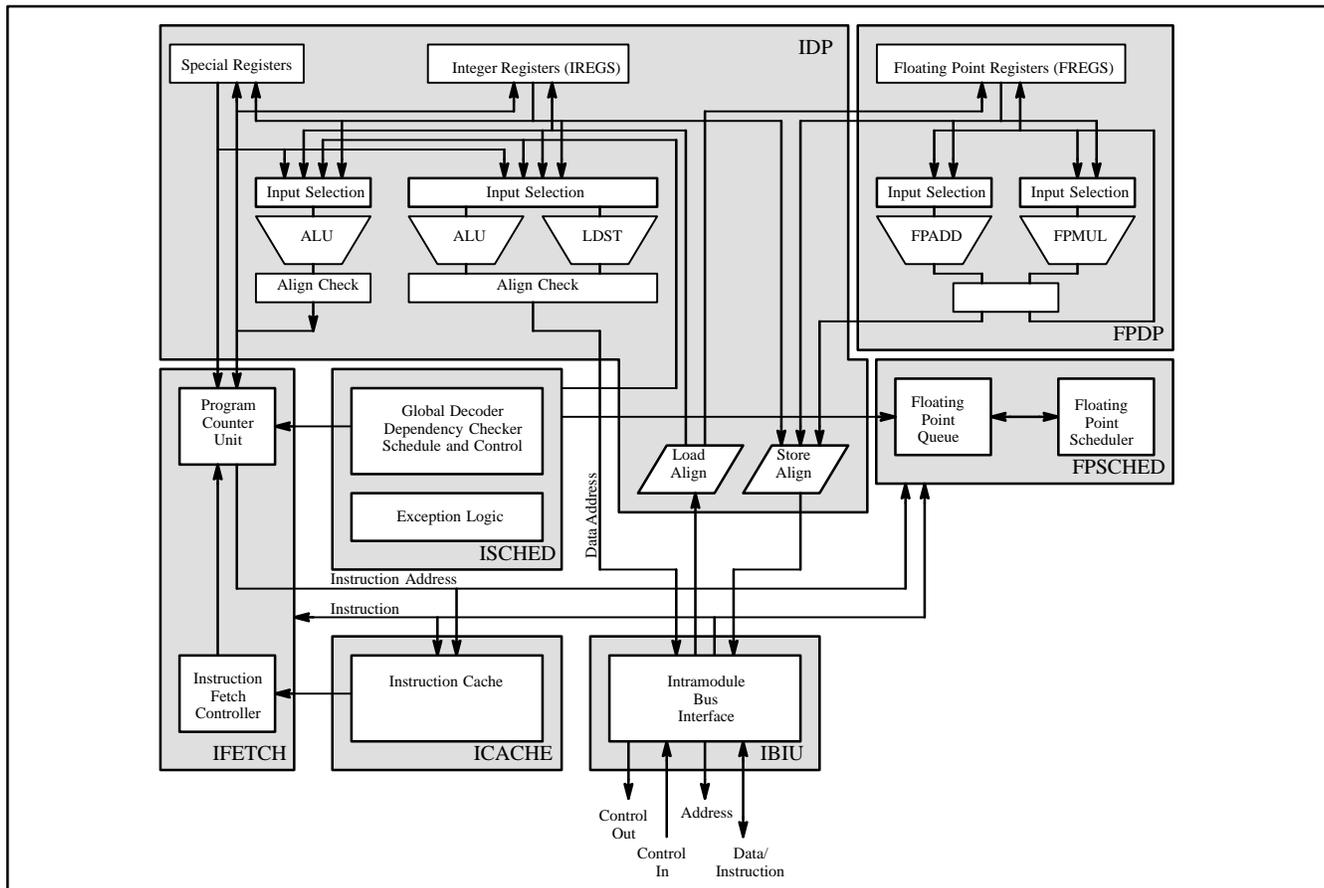


Figure 2. RT620C CPU Logic Block Diagram

Register Unit (SRU) handles instructions that read and write the SPARC Special Registers (SREGS). The Integer Register File (IREGS) is also contained in the IDP.

FPDP. The Floating-Point Data Path also comprises several units. These are the Floating-Point Queue (FPQ), the Floating-Point Arithmetic Unit (FAU), The Floating-Point Multiplier Unit (FMU), the Floating-Point Register File (FREGS), and the Floating-Point Status Register (FSR). These floating-point units handle all SPARC floating-point instructions.

ISCHED. The Integer Scheduler performs key control functions. It provides global instruction decodes to identify which execution unit resources are required, and determines whether sequential or simultaneous execution is possible.

The ISCHED also determines whether data forwarding can be performed and whether instruction dispatches (also called “launches”) need to be delayed due to data dependencies. The ISCHED initiates instruction launch and identifies and controls interrupt and trap handling.

FPSCHED. The Floating-Point Instruction Scheduler performs key control functions for the floating-point unit. When the Integer Unit detects floating-point instructions in the decode stage, it offloads these instructions to the floating-point functional units and continues processing. Therefore, functional blocks exist that perform necessary decode, scheduling, and control for the floating-point operations.

The FPSCHED performs floating-point instruction decoding, resolves floating-point data dependency and data-forwarding conditions, and provides the ISCHED with floating-point execution status. Delayed instructions are stored temporarily in the Floating-Point Instruction Queue (FPQ). Instructions are launched from the FPQ as data dependencies are resolved.

IFETCH. The Instruction Fetch Unit consists of two major functional blocks referred to as the Program Counter Unit (PCU) and the Instruction Fetch Controller (IFETCHC).

The PCU calculates the address of the next instruction to be fetched. It handles instructions that cause program control transfer, such as CALL and BRANCH. This unit handles both integer and floating-point branch instructions.

The IFETCHC fetches two instructions at a time, and in each clock cycle, the CPU attempts to launch both at once.

ICACHE. The on-chip instruction cache is organized as a two way set associative buffer. The ICACHE stores 8 Kbytes of instructions. Its inclusion follows the Harvard architecture approach, reducing bus contention during memory accesses. The ICACHE has a high-performance, one-wait-state cache miss penalty.

IBIU. The Intra-Module Bus Interface Unit provides the interface between the RT620C CPU and the external world. The IBIU samples incoming control signals and propagates controls to appropriate functional blocks. The IBIU is responsible for generating memory access control signals to the cache memory subsystem. Data and instructions are read from memory and data is written to memory, through the IBIU.

Cache Control, Memory Management, and Tag Unit (RT626)

The CMTU (RT626) is a combined Cache Controller and Memory Management Unit optimized for multiprocessing systems. The CMTU is a high-speed CMOS implementation of the SPARC Reference MMU, combined with cache, a memory controller, and on-chip physical cache tag memory. The CMTU supports the SPARC MBus Level 2 protocol for multiprocessing systems. *Figure 3* depicts the CMTU block diagram.

The CMTU directly connects to the RT620C Central Processing Unit and RT628 Cache Data Units without any external circuitry. The RT626 CMTU uses four or eight RT628 CDUs to realize 512-Kbytes or 1-Mbyte, respectively, of zero-wait-state, direct-mapped virtual cache memory.

MMU. The MMU portion of the CMTU provides translation from a 32-bit virtual address (4 gigabytes) to 36-bit physical address (64 gigabytes), as provided in the SPARC reference MMU specification. Virtual addresses are further extended with the use of a context register, which is used to identify up to 4096 contexts or tasks. The TLB entries contain context numbers to identify tasks or processes. This minimizes unnecessary TLB entry replacement during task switching.

The CMTU performs its address translation task by comparing a virtual address supplied by the RT620C through the Intra-Module Bus to the address tags in the TLB entries. If a “hit” occurs, the physical address stored in the TLB is used to translate the virtual-to-physical address. If the virtual address does not match any valid TLB entry, a “miss” occurs. This causes a table walk to be performed by the MMU. The table walk is a search performed by the MMU through the address translation tables stored in main memory. Upon finding the PTE, the MMU translates the address and selects a TLB entry for replacement.

Cache Controller The CMTU’s cache controller supports two modes of caching: write-through with no write allocate and copy-back with write allocate. The cache is “virtually indexed” and “physically tagged.”

In 1-Mbyte secondary cache versions, the cache is organized as 16384 lines with two sub-blocks, each of which is 32 bytes. Intra-Module Bus address bits IMA[19:6] select the cache line, IMA[5] selects the sub-block, and IMA[4:3] select the 64-bit word of the cache line. In 512-Kbyte secondary cache versions, only one sub-block is populated, and IMA[18:5] select the cache line and IMA[4:3] select the 64-bit word of the cache line.

The 16384 cache tag entries in the RT626 are virtual address indexed. From the processor side, the virtual address on the Intra-Module Bus is used to select a cache line entry and its corresponding cache tag entry. The translated physical address is then compared against the physical address in the selected cache tag entry to determine if the required data resides in the cache.

From the MBus side, the superset virtual address bits are concatenated with physical address bits [11:5] to select a cache

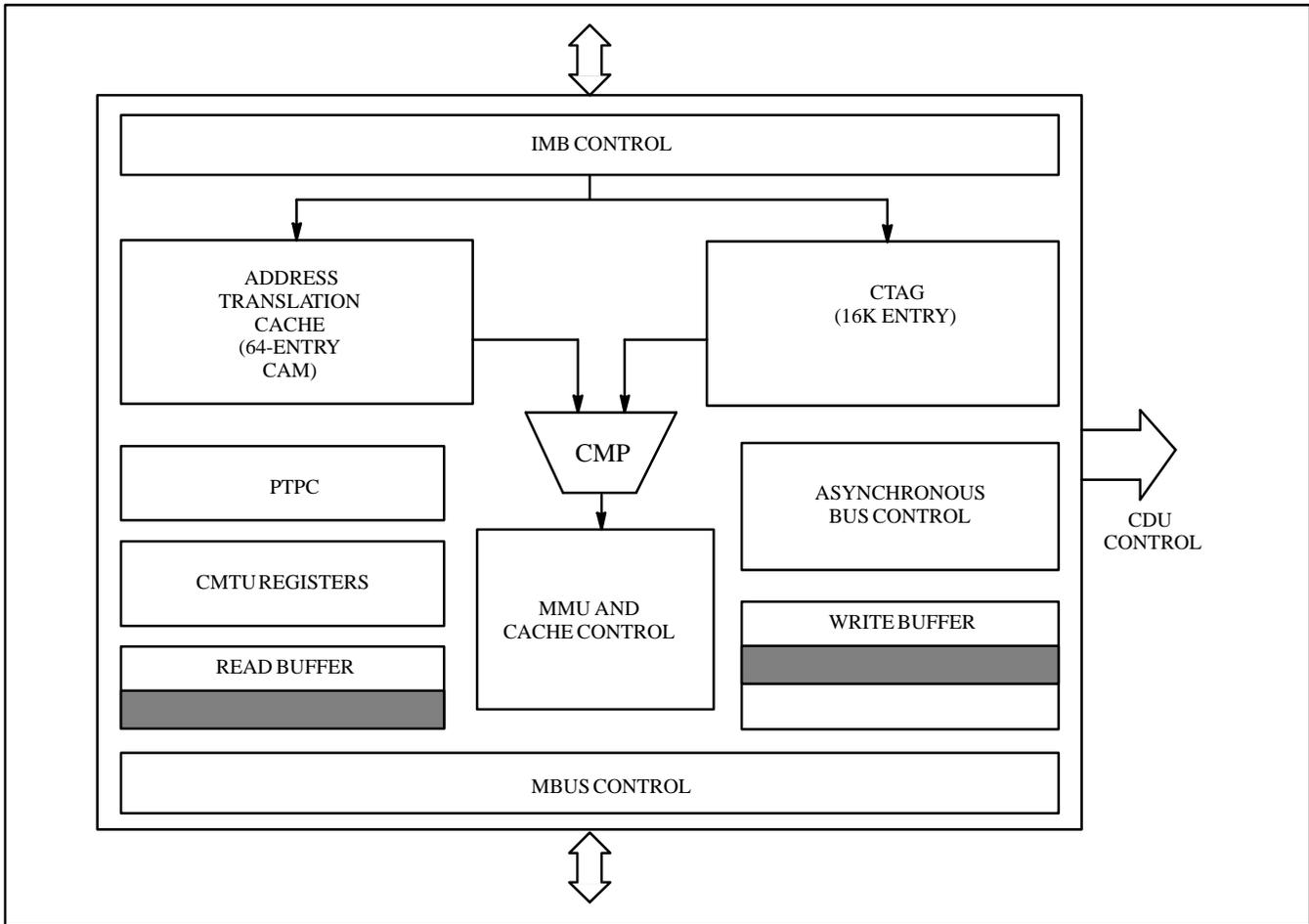


Figure 3. RT626 CMTU Block Diagram

line entry and its corresponding cache tag entry. The physical address on MBus is then compared against the physical address in the selected cache tag entry to determine if the required data resides in the cache.

A 64-byte write buffer and a 32-byte read buffer are provided in the RT626 to fully buffer the transfer of cache lines. This feature allows the CMTU to simultaneously read a cache line from main memory as it flushes a modified cache line from the cache.

MBus. The CMTU supports the SPARC MBus interface standard and the SPARC MBus Level 2 cache coherency protocol. It supports data transfers in transaction sizes of 1, 2, 4, 8, or 32 bytes. These data transfers are performed in either burst or non-burst mode, depending upon the size. Data transactions larger than 8 bytes are transferred in burst mode. Bus mastership is granted and controlled by an external bus arbiter.

The CMTU also supports the MBus Module Identifier feature of the MBus, in which it accepts the Module Identifier input from the MBus and embeds it in the MBus address phase of all MBus transactions initiated by the CMTU.

Cache Data Units (RT628)

The RT628 is organized as four arrays of 32-Kbytes each. It contains one-deep write buffer pipelines, byte write logic, registered inputs, data-in and data-out latches, and data forwarding logic for the write buffer.

Writing into the RAM core is delayed until the next write access. To allow data forwarding, the CDU incorporates a comparator to compare the address of the write-buffer to the incoming read address. If a match occurs, data is forwarded directly from the write-buffer to satisfy the current read cycle.

For a more complete description of the individual SPARC components used in the RT6226N, please refer to the *ROSS SPARC RISC User's Guide* and *Appendix B*.

Power Module

The RT6226N2 power module utilizes two integrated switching regulators in a current sharing configuration. It receives +5V from the CPU module and converts it to the low voltage required by the CPUs. It is capable of supplying up to 16 A to the CPUs at a typical conversion efficiency greater than 80%.

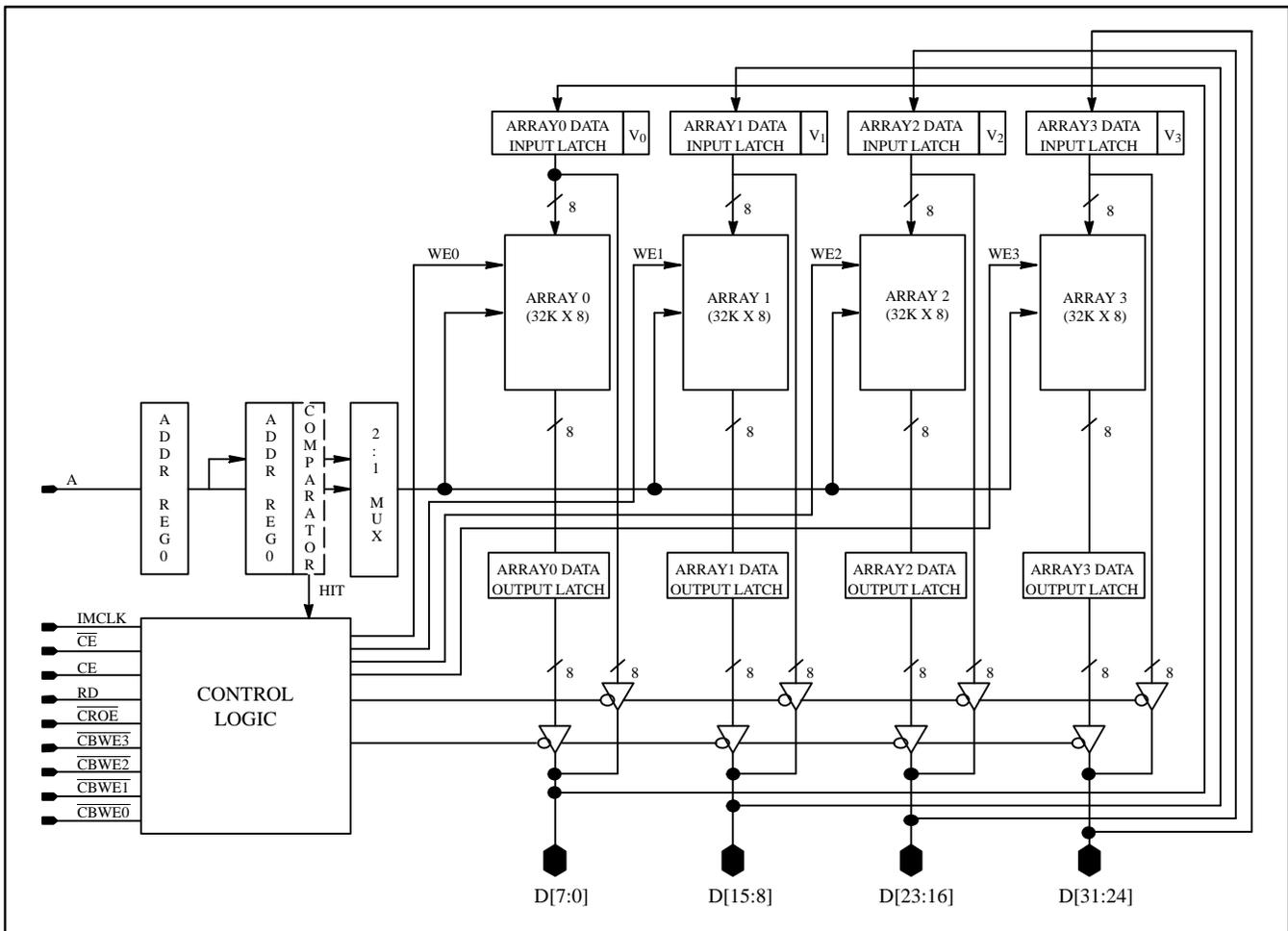


Figure 4. RT628 Block Diagram

CPU Module Design

Advanced Packaging Technology

The RT6226N1 employs multi-die packaging (MDP) technology to facilitate higher clock frequencies and reliable operation. Each MDP component contains a complete hyper-SPARC CPU chipset. MDP technology improves electrical characteristics by reducing electrical parasitics, allowing multiple discrete chips to function as a single monolithic die.

Clock Distribution

The RT6226N1 uses three MBus clock signals (MCLK[0], MCLK[1], and MCLK[2]) as defined in the MBus Specification. In order to minimize clock skew, traces have been carefully routed. All clock lines are routed on inner layers of the module PCB, and their lengths and impedances are matched. The MBus clock lines have diode termination to reduce signal undershoot and overshoot, and all intramodule clock lines use a parallel resistive termination of 60Ω.

MBus Connector (Module)

The RT6226N1 interface is via the 100-pin SPARC MBus connector, which is a two-row male connector with 0.050" spacing (AMP part number 121354-4 or Fujitsu part number

FCN-264P100-G/C). The connector is a controlled impedance-type (50Ω ±10%) based on a microstrip configuration that provides a controlled characteristic impedance plus very low inductance and capacitance. Separate power and ground blades are provided for isolation to prevent noise transference. *Table 1* details the RT6226N standard connector pinout. This MBus connector supports Level 2 MBus.

Mating MBus Connector (System Interface Board)

The module connects to the system interface through the standard MBus female connector (vertical receptacle assembly, AMP part number 121340-4 or Fujitsu FCN-264J100-G/0).

Reset and Interrupt Signals

A power-on reset signal is generated to the module from the MBus via the RSTIN signal. Each CPU has its own direct set of interrupt lines. Level sensitive interrupts (15 max) are generated to each RT620 via the MIRL0[3:0] and MIRL1[3:0] lines from the MBus. A value of 0000b means that there is no interrupt, while a value of 1111b means an NMI (Non-Maskable Interrupt) is being asserted. MIRL

Colorado 3 RT6226N

values between 1 and 14 represent interrupt requests that can be masked by the processor.

MBus Request and Grant Signals

Two separate sets of request and grant signals ($\overline{\text{MBR}}[0]$ and $\overline{\text{MBG}}[0]$ for CPU0, $\overline{\text{MBR}}[1]$ and $\overline{\text{MBG}}[1]$ for CPU1) are generated to/from the RT6226N modules to arbitration logic on the motherboard.

MBus SCAN Test Feature

The RT6226N module also supports the Boundary SCAN test feature of the MBus. For more details on the SCAN test,

please refer to the *ROSS SPARC RISC User's Guide* and *SPARC MBus Interface Specification*.

MID Lines

Each CPU on the RT6226N1 has a dedicated set of MID[3:0] lines. To ensure that each CPU has a unique MID number the module ties CPU0 (Channel 0) MID[0] to ground and CPU1 (Channel 1) MID[0] to V_{CC} .

Table 1. MBus Connector Pinout ^[1]

Pin #	Signal Name	Blade	Pin #	Signal Name	Pin #	Signal Name	Blade	Pin #	Signal Name
1	TDI	Blade #1	2	TMS	51	MCLK[2]	Ground	52	$\overline{\text{MERR}}$
3	TDO	Ground	4	$\overline{\text{TRST}}$	53	MCLK[3]		54	$\overline{\text{MAS}}$
5	TCLK		6	MIRL0[1]	55	$\overline{\text{MBR}}[1]$	Ground	56	$\overline{\text{MBB}}$
7	MIRL0[0]	Ground	8	MIRL0[3]	57	$\overline{\text{MBG}}[1]$		58	RSVD0
9	MIRL0[2]		10	RES	59	MAD[32]		60	MAD[33]
11	MAD[0]	Ground	12	MAD[1]	61	MAD[34]	Blade #4	62	MAD[35]
13	MAD[2]		14	MAD[3]	63	MAD[36]	V_{CC}	64	MAD[37]
15	MAD[4]	Ground	16	MAD[5]	65	MAD[38]		66	MAD[39]
17	MAD[6]		18	MAD[7]	67	MAD[40]	V_{CC}	68	MAD[41]
19	MAD[8]		20	MAD[9]	69	MAD[42]		70	MAD[43]
21	MAD[10]	Blade #2	22	MAD[11]	71	MAD[44]	V_{CC}	72	MAD[45]
23	MAD[12]	V_{CC}	24	MAD[13]	73	MAD[46]		74	MAD[47]
25	MAD[14]		26	MAD[15]	75	MAD[48]	V_{CC}	76	MAD[49]
27	MAD[16]	V_{CC}	28	MAD[17]	77	MAD[50]		78	MAD[51]
29	MAD[18]		30	MAD[19]	79	MAD[52]		80	MAD[53]
31	MAD[20]	V_{CC}	32	MAD[21]	81	MAD[54]	Blade #5	82	MAD[55]
33	MAD[22]		34	MAD[23]	83	MAD[56]	Ground	84	MAD[57]
35	MAD[24]	V_{CC}	36	MAD[25]	85	MAD[58]		86	MAD[59]
37	MAD[26]		38	MAD[27]	87	MAD[60]	Ground	88	MAD[61]
39	MAD[28]		40	MAD[29]	89	MAD[62]		90	MAD[63]
41	MAD[30]	Blade #3	42	MAD[31]	91	RSVD1	Ground	92	MIRL1[0]
43	$\overline{\text{MBR}}[0]$	Ground	44	$\overline{\text{MSH}}$	93	MIRL1[1]		94	MIRL1[2]
45	$\overline{\text{MBG}}[0]$		46	$\overline{\text{MIH}}$	95	MIRL1[3]	Ground	96	$\overline{\text{AERR}}$
47	MCLK[0]	Ground	48	$\overline{\text{MRTY}}$	97	$\overline{\text{RSTIN}}$		98	MID[1]
49	MCLK[1]		50	$\overline{\text{MRDY}}$	99	MID[2]		100	MID[3]

Notes:

- RES and RSVD pins are not used in the RT6226N but reserved for other MBus module upgrades. See the System Design Considerations section

for the assignment of these reserved pins per the SPARC MBus Specification.

Table 2. Power Connector Pinout

Pin #	Signal Name	Pin #	Signal Name	Pin #	Signal Name	Pin #	Signal Name
1	Chassis GND	2	GND	3	V_{CC0}	4	V_{CC0}
5	V_{CC0}	6	V_{CC0}	7	GND	8	NC
9	NC	10	NC	11	V_{CC} Sense	12	NC
13	Chassis GND	14	GND	15	GND	16	GND
17	GND	18	GND	19	V_{CC0} Sense	20	ADJUST
21	V_{CC}	22	V_{CC}	23	V_{CC}	24	V_{CC}
25	GND						

Processor Module Electrical Specifications
Absolute Maximum Ratings ^[2] (Provided as guidelines; not tested.)

Parameter	Description	Rating	Units	
V _{CC}	Supply Voltage Range	-0.5 to +6.0	V	
V _{CCO}	Low Supply Voltage Range	-0.5 to +3.8	V	
P _D	Maximum Power Consumption	60	W	
I _{CC}	Maximum High Supply Current	V _{CC} = 5.0V	1	A
I _{CCO}	Maximum Low Supply Current	V _{CCO} = 3.5V	16	A
V _I	Input Voltage Range	-0.3 to +7.0	V	
T _{STG}	Storage Temperature	-20 to +75	°C	
RH _{STG}	Storage Relative Humidity ^[3]	5 to 80	%	

Recommended Operating Conditions ^[4]

Parameter	Description	Min.	Typ.	Max.	Units
V _{CC}	Supply Voltage	4.8	5.00	5.25	V
V _{CCO}	Low Supply Voltage	3.3	3.5	3.6	V
V _{IH}	Input HIGH Voltage	Signals referenced to V _{CC}	2.1	V _{CC}	V
		Signals referenced to V _{CCO}	2.1	V _{CCO}	V
V _{IL}	Input LOW Voltage	-0.5		0.8	V
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = -2.0 mA	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA		0.5	V
I _{IZ}	Input Leakage Current (non-clock pins)	V _{CC} = Max., V _{SS} ≤ V _{OUT} ≤ V _{CC}	-10	+10	μA
I _{CLKZ}	Input Leakage Current (clock pins)	V _{CC} = Max., V _{SS} ≤ V _{OUT} ≤ V _{CC}	-40	+40	μA
I _{OZ}	Output Leakage Current	V _{CC} = Max., V _{SS} ≤ V _{OUT} ≤ V _{CC}	-15	+15	μA
I _{SC}	Output Short Circuit Current ^[5]	V _{CC} = Max., V _{OUT} = 0V	-30	-350	mA
T _A	Operating Ambient Air Temperature ^[6]	0		50	°C
RH _{OP}	Operating Relative Humidity ^[3]	5		95	%

Capacitance ^[7]

Parameter	Description	Max.	Units
C _{IN}	Input Capacitance	36	pF
C _{OUT}	Output Capacitance	40	pF
C _{IO}	Input/Output Capacitance	46	pF
C _{INCLK}	Clock Input Capacitance	28	pF

V_{CC} = 5.0V
 T_A = 25°C
 f = 1 MHz

Notes:

- All power and ground pins must be connected to other pins of the same type before any power is applied to the RT6226N1. At least three clock cycles must be applied to set up the internal chip drivers properly.
- Non-condensing. Maximum rate of change of 30% per hour.
- Recommended use of this module does not include "hot-socketing" or "live-insertion" (i.e., it is not recommended that the RT6226N1 be placed in the MBus socket with the power supply on).
- Not more than one output should be tested at one time. Duration of the short circuit should not be more than one second.
- See Appendix A. hyperSPARC Module Thermal Specifications. This temperature should not be exceeded when the device is consuming maximum power with 300 linear feet per minute (LFM) airflow at sea level.
- Tested initially and after any design or process changes that may affect these parameters.

Power Module Electrical Specifications

Absolute Maximum Ratings ^[8] (Provided as guidelines; not tested.)

Parameter	Description	Rating	Units
V _{CC}	Supply Voltage Range	+4.8 to +6.0	V
P _D	Maximum Power Dissipation	17	W
I _{SC}	Short Circuit Current, V _{CC} = 5.0V	30	A pk
T _{STG}	Storage Temperature	-20 to +75	°C
RH _{STG}	Storage Relative Humidity ^[9]	5 to 80	%

Recommended Operating Conditions ^[10]

Parameter	Description	Min.	Typ.	Max.	Units
V _{CC}	Supply Voltage	4.8	5.00	5.25	V
V _{CCO}	Low Supply Voltage	3.3	3.5	3.6	V
I _{CC}	Input Current, V _{CC} = 5.0V		14	16	A
I _{CCO}	Output Current, V _{CCO} = 3.5V	0.2	16	18	A
REG _{LOAD}	Load Regulation	V _{CC} = 5.0V, 0.1 ≤ I _{CCO} ≤ 16.0A		±25	mV
V _N	Ripple/Noise	V _{CC} = 5.0V, I _{CCO} = 16.0A		50	mV
η	Conversion Efficiency	V _{CC} = 5.0V, I _{CCO} = 16.0A		80	%
T _A	Operating Ambient Air Temperature ^[11]	0		40	°C
RH _{OP}	Operating Relative Humidity ^[9]	5		95	%

Notes:

8. All power and ground pins must be connected to other pins of the same type before any power is applied to the RT6226N2.
9. Non-condensing. Maximum rate of change of 30% per hour.
10. Recommended use of this module does not include "hot-socketing" or "live-insertion" (i.e., it is not recommended that the RT6226N2 be plugged into the RT6226N1 when power is applied).
11. See Appendix A. hyperSPARC Module Thermal Specifications. This temperature should not be exceeded when the device is consuming maximum power with 200 linear feet per minute (LFM) of airflow at sea level.

AC Electrical Characteristics Over the Operating Range ^[12,13]

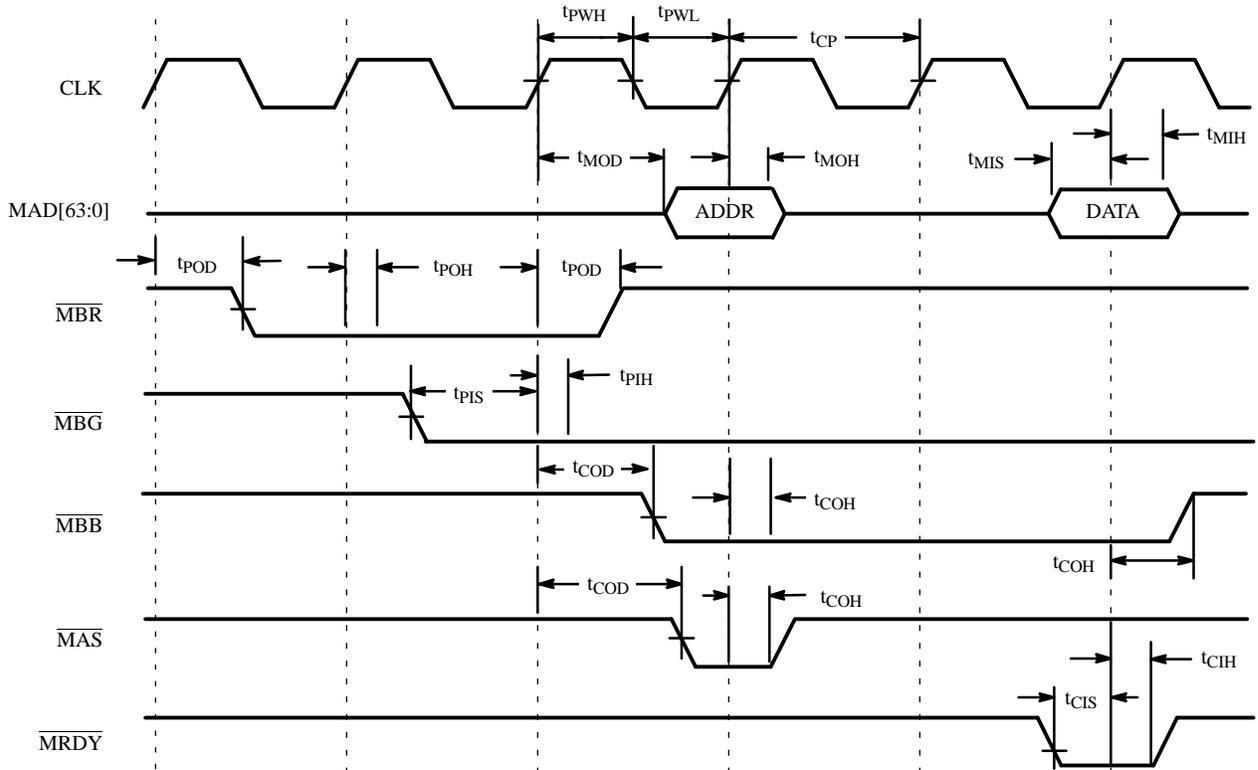
Param	Description	50 MHz MBus		66 MHz MBus		Unit
		Min.	Max.	Min.	Max.	
Synchronous signals ^[14]						
t _{CP}	MBus Clock period	20		15		ns
t _{PWH}	MBus Clock High period	9.2		6.9		ns
t _{PWL}	MBus Clock Low period	9.2		6.9		ns
t _{CSR}	MBus Clock Slew Rate (between 0.8V and 2.0V)	0.8		0.8		V/ns
t _{SKU}	MBus Clock Skew ^[15]		1.0		0.5	ns
t _{MOD}	MAD(63:0) Output Delay		13.5		11.0	ns
t _{MOH}	MAD(63:0) Output Valid	4.0		2.5		ns
t _{MIS}	MAD(63:0) Input Set-Up	3.5		3.5		ns
t _{MIH}	MAD(63:0) Input Hold	2.0		2.0		ns
t _{COD}	MBus Bused Control Output Delay		13.5		10.5	ns
t _{COH}	MBus Bused Control Output Valid	4.0		2.5		ns
t _{CIS}	MBus Bused Control Input Set-Up	5.5		3.5		ns
t _{CIH}	MBus Bused Control Input Hold	2.0		2.0		ns
t _{POD}	MBus Point-to-Point Control Output Delay		13.5		10.5	ns
t _{POH}	MBus Point-to-Point Control Output Valid	4.0		2.5		ns
t _{PIS}	MBus Point-to-Point Control Input Set-Up	5.5		3.5		ns
t _{PIH}	MBus Point-to-Point Control Input Hold	2.0		2.0		ns
Asynchronous Signals						
t _{RST}	MBus Reset Duration ^[16]	100		100		ms

Notes:

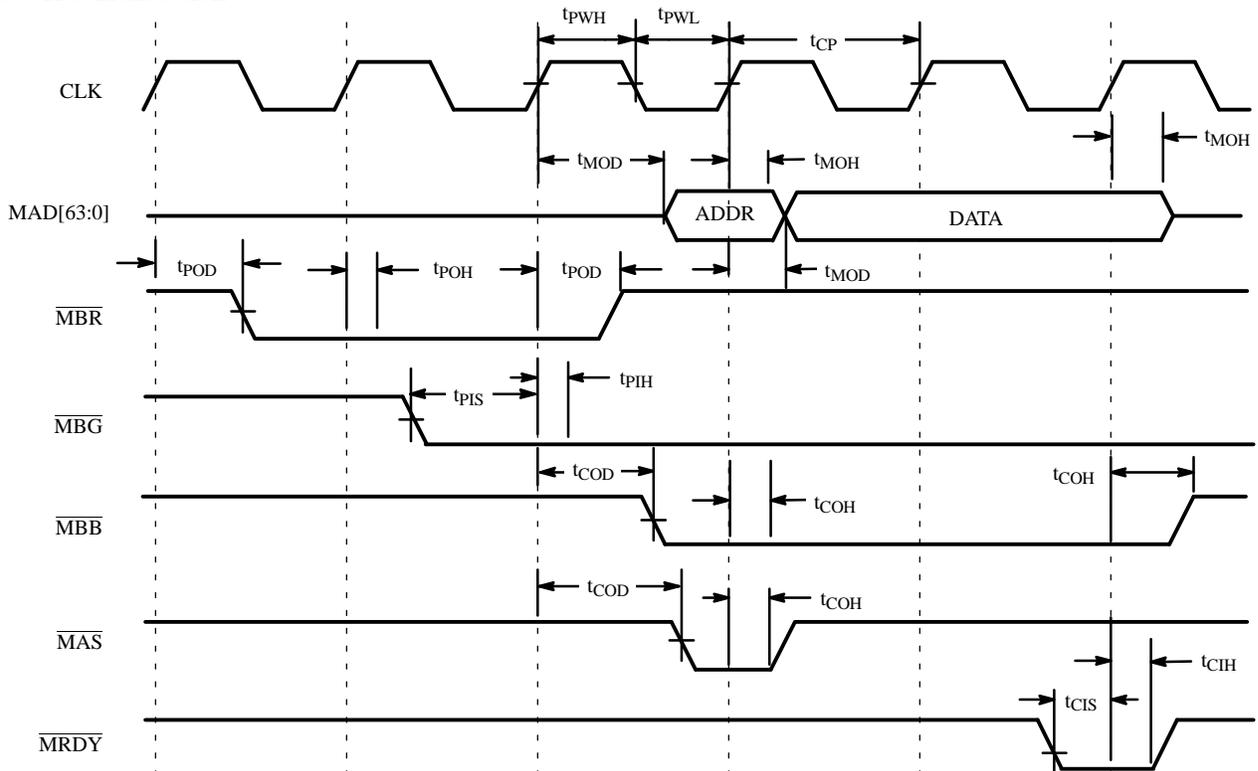
12. Test conditions assume signal transition times of 3 ns or less, a timing reference level of 1.5V, input levels of 0 to 3.0V, and output loading of 120-pF capacitance, not including the module itself (with the exception of MBus point-to-point control signals, tested with an output loading of 40 pF).
13. All measurements made at MBus connector.
14. All timing parameters are relative to one of the two processors (e.g., t_{MOD} is guaranteed relative to MCLK[0]).
15. Measured between any two MCLK signals.
16. This is the minimum time for which RSTIN must be asserted after both high and low power supply voltages are stable.

MBus Timing Diagrams

Single Read Transaction



Single Write Transaction



System Design Considerations

The RT6226N1 implements all but one of the possible MBus signals. The MBus connector, per the SPARC MBus Specification, assigns the optional signal $\overline{\text{INTOUT}}$ to Pin 10. Although this signal is not used on the RT6226N, systems designers should be aware of this assignment to preserve compatibility with other MBus modules.

Table 3. Pins Reserved on RT6226N1

Pin #	Signal Name
10	$\overline{\text{INTOUT}}$
58*	RSVD0
91*	RSVD1

* Non-floating. Reserved for ROSS internal use only. These signals should not be driven.

All MAD, based control, and point to point control signals use 8-mA drivers. The $\overline{\text{MSH}}$ and $\overline{\text{AERR}}$ signals use open-drain drivers.

10-Kohm pull up resistors are required on $\overline{\text{MAS}}$, $\overline{\text{MRDY}}$, $\overline{\text{MRTY}}$, $\overline{\text{MERR}}$, $\overline{\text{MBB}}$, and $\overline{\text{MIH}}$. A 1.5-Kohm pull up resistor is recommended on $\overline{\text{AERR}}$. A 619 ohm pull up resistor is recommended on $\overline{\text{MSH}}$. MAD signals require holding amplifiers.

In order to assure that all module scan circuitry is initialized to the normal operating state on reset, the following is recommended for the MBus scan signals. TDI and TMS should be pulled up to 5V with 10K Ω resistors. TCLK must toggle at least 3 full cycles while $\overline{\text{TRST}}$ is asserted in order to reset all scan circuitry. $\overline{\text{RSTIN}}$ may be driven by the module when the module is in scan mode, so it should be buffered from the rest of the system. These requirements may be met by connecting each signal as shown in Figure 5. The RT6226N1 uses MCLK[0] to clock processor 0, MCLK[2] to clock processor 1, and MCLK[1] for test.

As the frequency of operation increases, transmission line effects play a bigger role. Care must be taken to keep skew between any two clock signals at the MBus connector within the specifications given in the Synchronous Signals table in the AC Characteristics section. MBus signal lines must be routed carefully to minimize crosstalk and interference. A thorough SPICE analysis of the motherboard design is recommended.

Use of HH Smith #4387 (3/4" length by 1/4" OD) stand-offs or equivalent is recommended on the motherboard to support the module and prevent damage to the connector.

If mounting screws are used, nylon screws are recommended to prevent over-torquing and damage to the PCB.

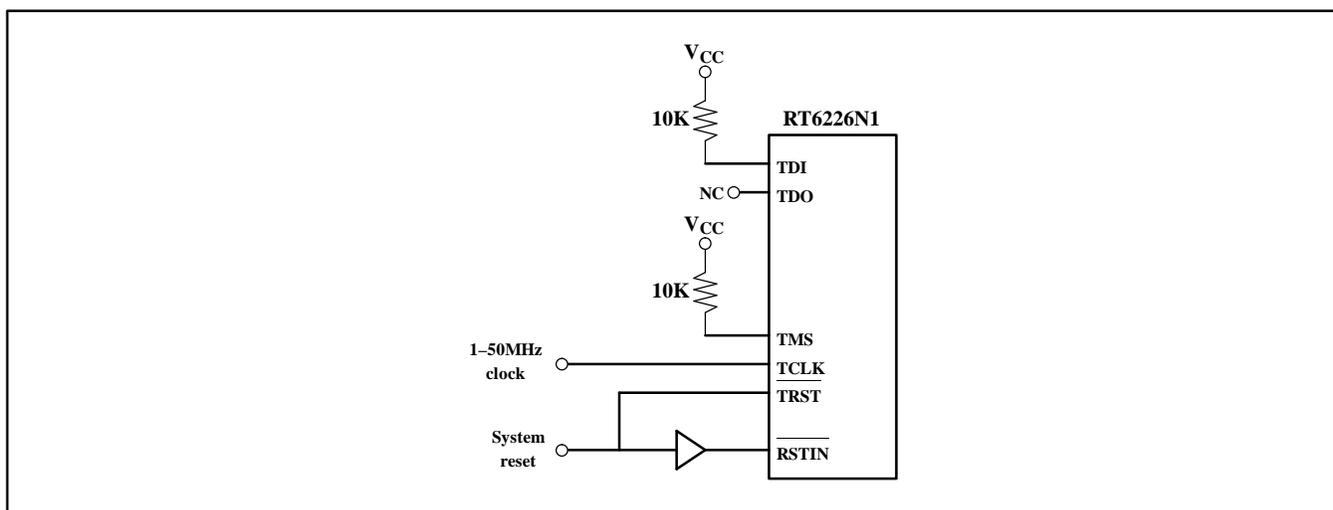


Figure 5. Scan Pin Connections

RT6226N1 Mechanical Drawing [17,18, 19]

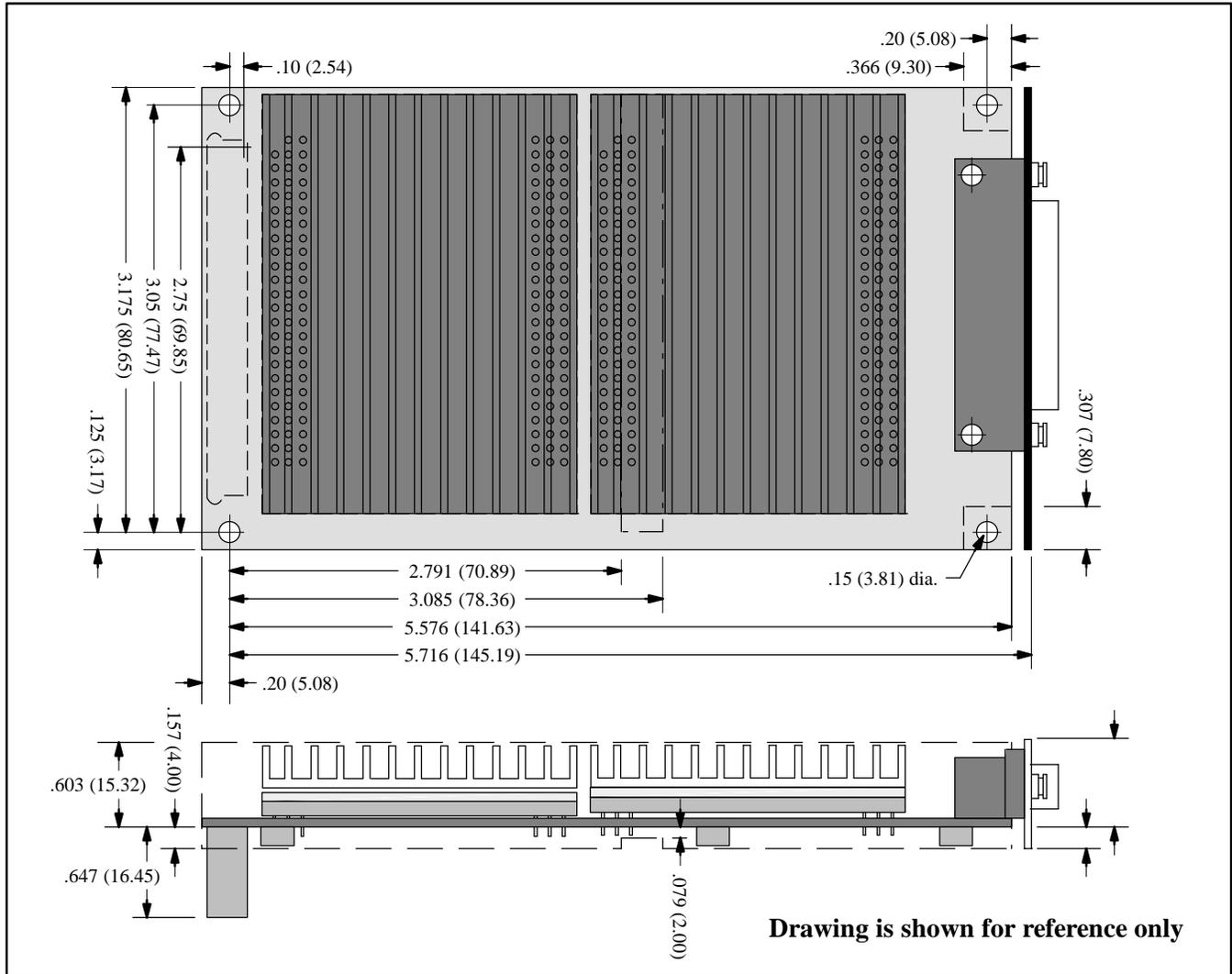


Figure 6. RT6226N1 Mechanical Dimensions

Notes:

- 17. Drawing is for reference only. Appearance of module is subject to change without notice.
- 18. Drawing is not to scale. All dimensions are in inches (mm).
- 19. To ensure compliance with all future MBus modules, systems developers should design to the MBus module envelope per the SPARC MBus Specification.

RT6226N2 Mechanical Drawing [20,21]

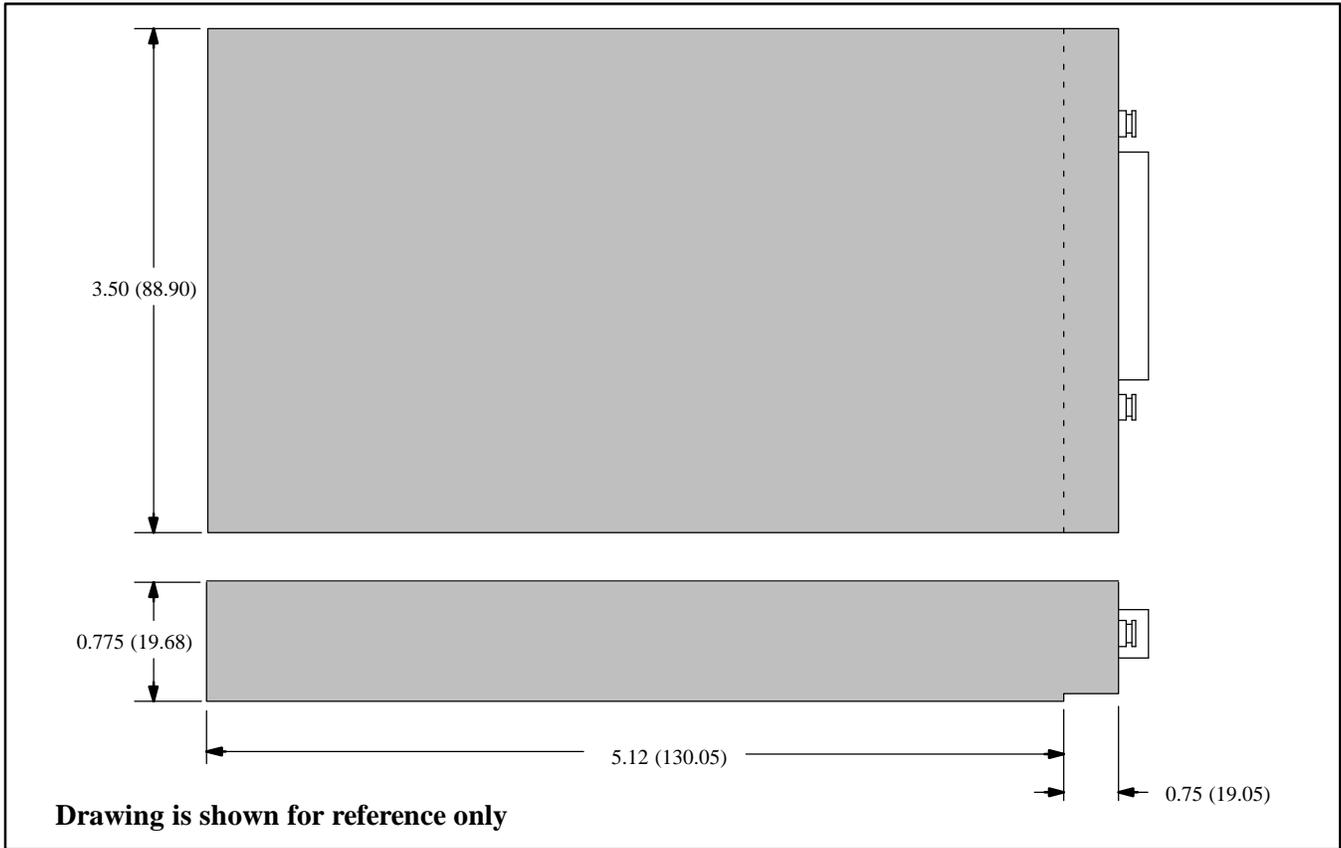


Figure 7. RT6226N2 Mechanical Dimensions

Notes:

17. Drawing is for reference only. Appearance of module is subject to change without notice.
18. Drawing is not to scale. All dimensions are in inches (mm).

RT6226N1 Labeling

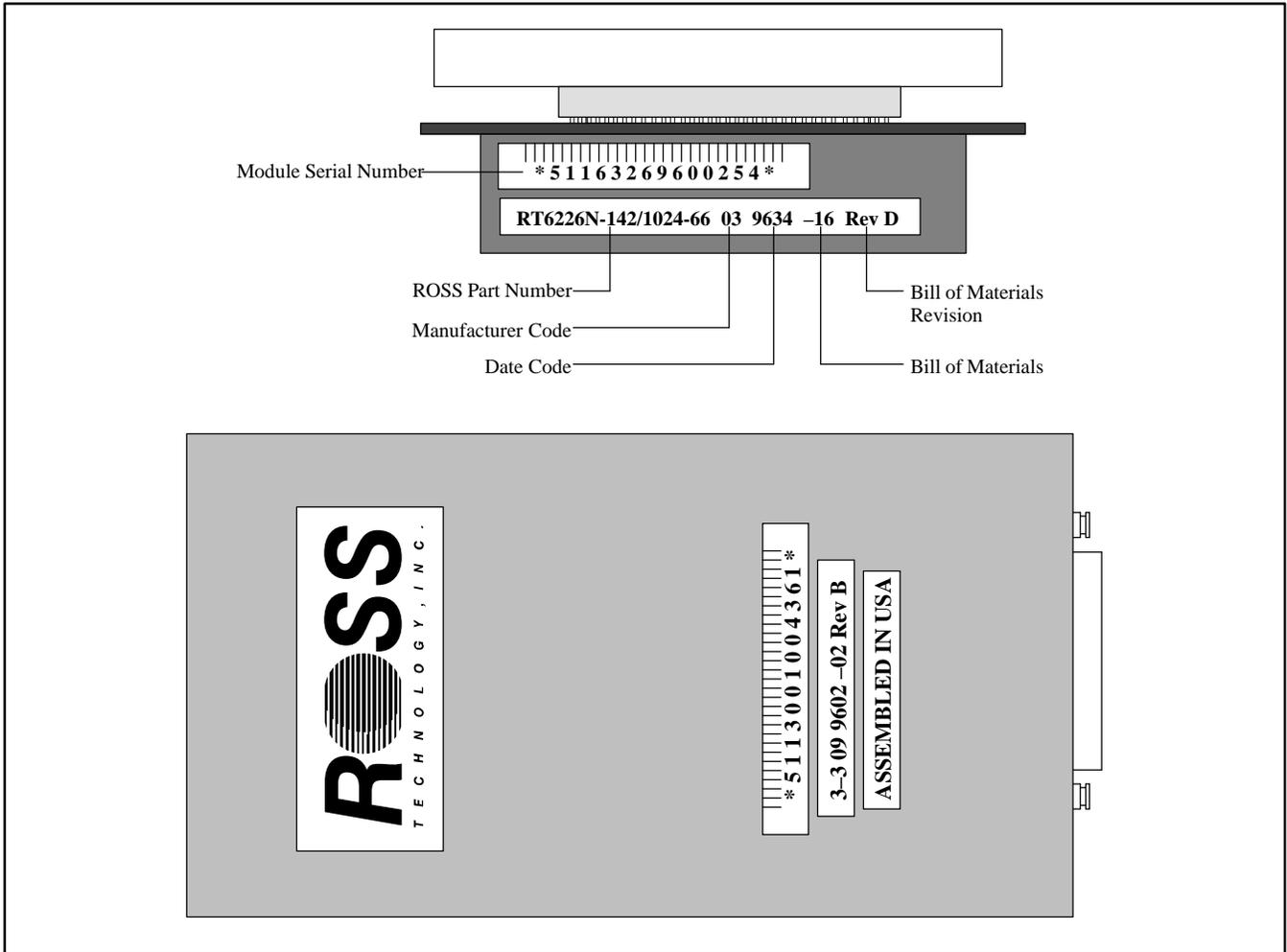


Figure 8. RT6226N Labeling

Appendix A. hyperSPARC Module Thermal Specifications

Processor Module

Ambient Temperature

Ambient temperatures as high as 50°C are acceptable for the RT6226N1 provided airflow is 300 linear feet per minute (LFM) minimum through the heatsink fins at all locations indicated in *Figure 9*. In this context, ambient temperature is defined as the air temperature in immediate proximity to the module.

Module airflow measurements must be taken with the anemometer probe in front of the fins, approximately 1/2”

above the top of the PCB at the indicated locations. The airflow must meet the minimum requirements at all locations indicated in *Figure 9*. When taking airflow measurements the module should be installed in a system that is configured in the same fashion as the actual final production system (for example, all external covers and panels should be installed, and any internal ducting or baffling should also be installed).

Ambient temperature should be measured within the system, as it enters the fins of the heatsinks on the module.

For further information regarding thermal measurements contact ROSS Applications Engineering.

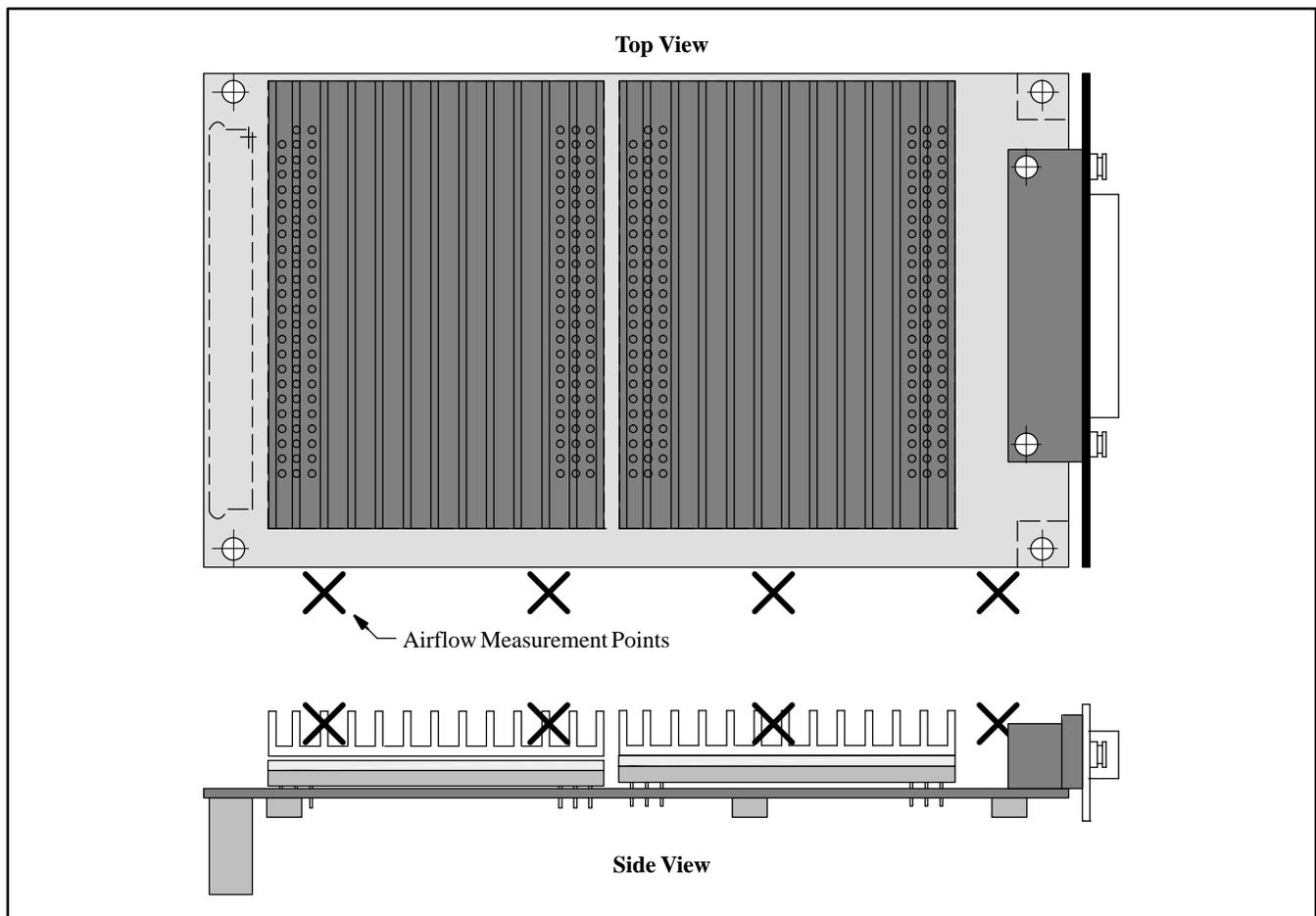


Figure 9. RT6226N1 Airflow Measurement

Appendix B. Impact of Cache Size on System Design.

Hardware Differences

hyperSPARC modules with 256-Kbytes of secondary cache utilize the RT625 Cache Controller, Memory Management, and Tag Unit (CMTU) and four RT627 Cache Data Units (CDUs). Modules with 512-Kbytes or 1-Mbytes of secondary cache utilize the RT626 CMTU and either four or eight RT628 CDUs.

CDU. The RT628 is functionally equivalent to the RT627 described in the *ROSS SPARC RISC User's Guide* except that the RT628 is based on a 32-Kbyte x 32-bit SRAM core.

CMTU. The RT626 is functionally equivalent to the RT625 described in the *ROSS SPARC RISC User's Guide*, with the few exceptions outlined below.

The RT626 supports two cache sizes: 512-Kbyte and 1-Mbyte. Cache lines are directly addressed by the RT620 CPU with the Intra-Module Address Bus (IMA[31:0]). The 512-Kbyte cache is organized into 16384 lines of 32 bytes each. IMA[18:5] select the cache line, and IMA[4:3] select the 64-bit word of the cache line, as illustrated in *Figure 10*. The 1-Mbyte cache is organized into 16384 lines with two sub-blocks, each sub-block being 32 bytes. Address bits IMA[19:6] select the cache line, address bit IMA[5] selects the sub-block, and address bits IMA[4:3] select the 64-bit word of the cache line, as illustrated in *Figure 11*.

The RT626 cache tag array consists of 16384 direct-mapped physical address cache tag entries. The layout of the cache tag entries is identical to that of the RT625. The 16384 CTAG entries are virtual address indexed.

From the processor side, the cache line select field, IMA[18:5] in the case of the 512-Kbyte cache or IMA[19:6] in the case of the 1-Mbyte cache, is used to select a cache line entry and its corresponding cache tag entry.

From the MBus side, the index field for CTAG, as supplied by the MBus, is formed by concatenating the superset virtual address bits [18:12] (MAD[52:46]) in the case of 512-Kbyte cache or [19:12] (MAD[53:46]) in the case of 1-Mbyte cache with physical address bits [11:5] (MAD[11:5]) as shown in *Figure 9* and *10*.

The System Control Register (SCR) is the same in both the RT625 and RT626, except for the *Cache Size* bit (SCR[12]). In the RT626, CS=0 indicates a 512-Kbyte cache subsystem, and CS=1 indicates a 1-Mbyte cache subsystem.

RT626 CTAG entries may be accessed using word LDST Alternate instructions with the cache tag entry address and ASI=0x0E. Each tag entry can be read as a Load single or can be written as a Store single by the RT620. The address mapping for the Cache Tag entries is shown in *Table 4*.

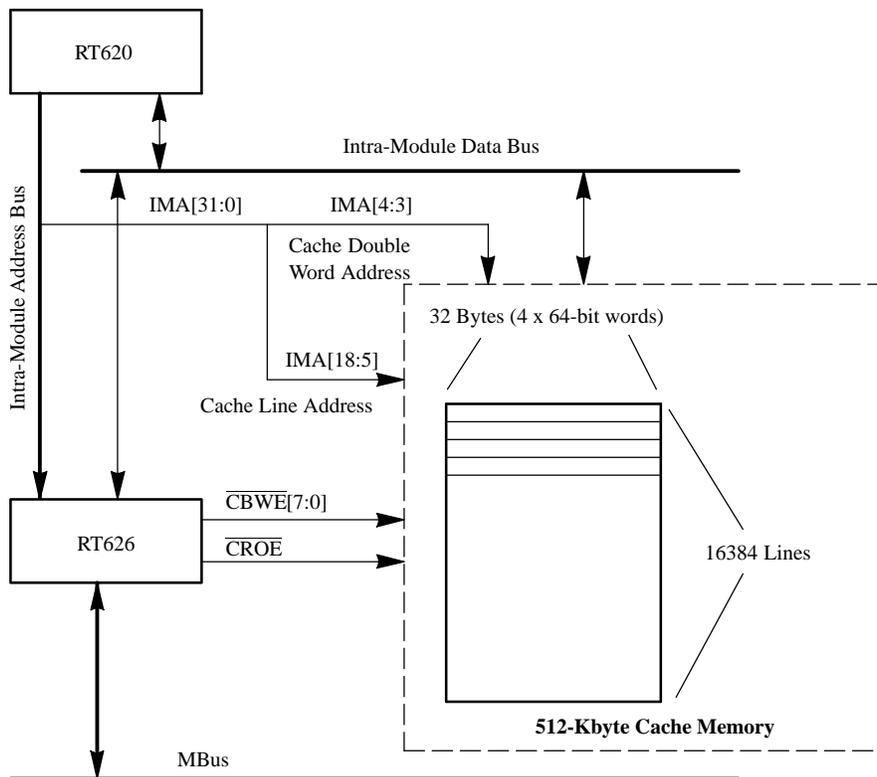


Figure 10. 512-KByte Cache Memory Subsystem

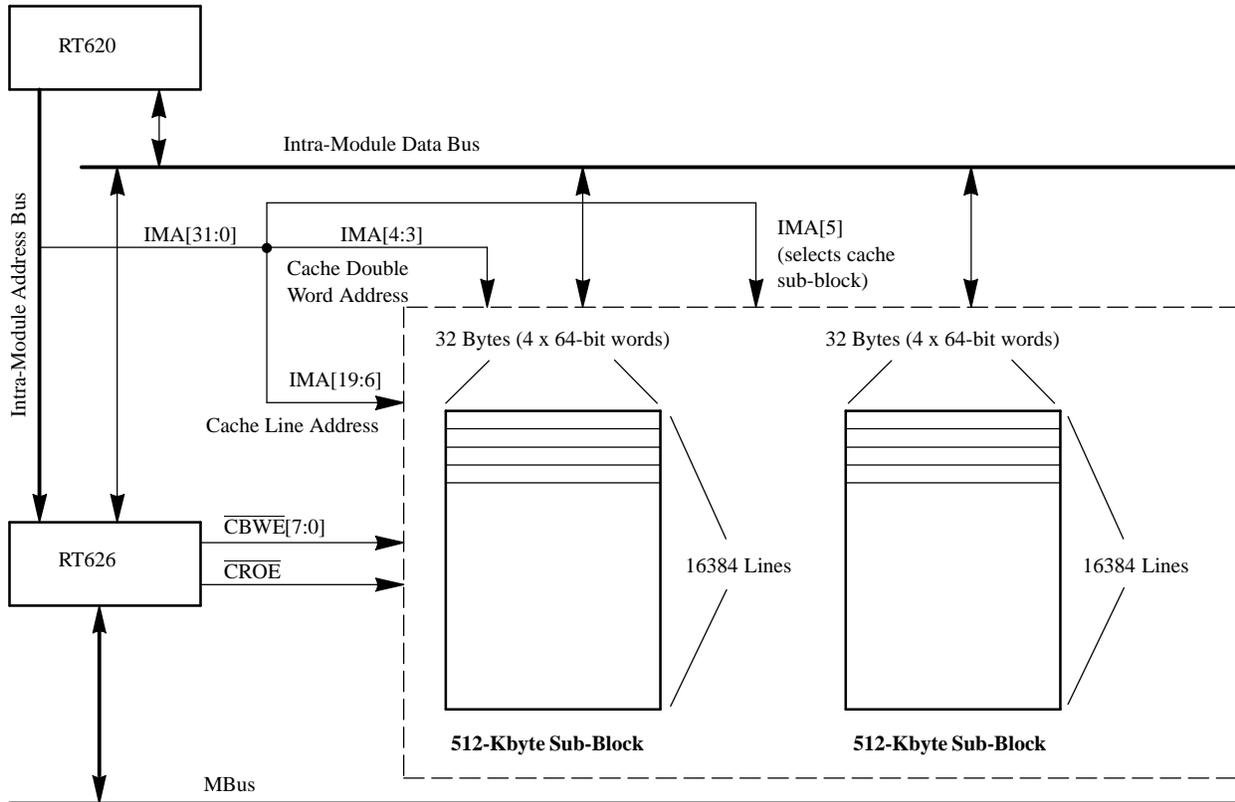


Figure 11. 1-Mbyte Cache Memory Subsystem

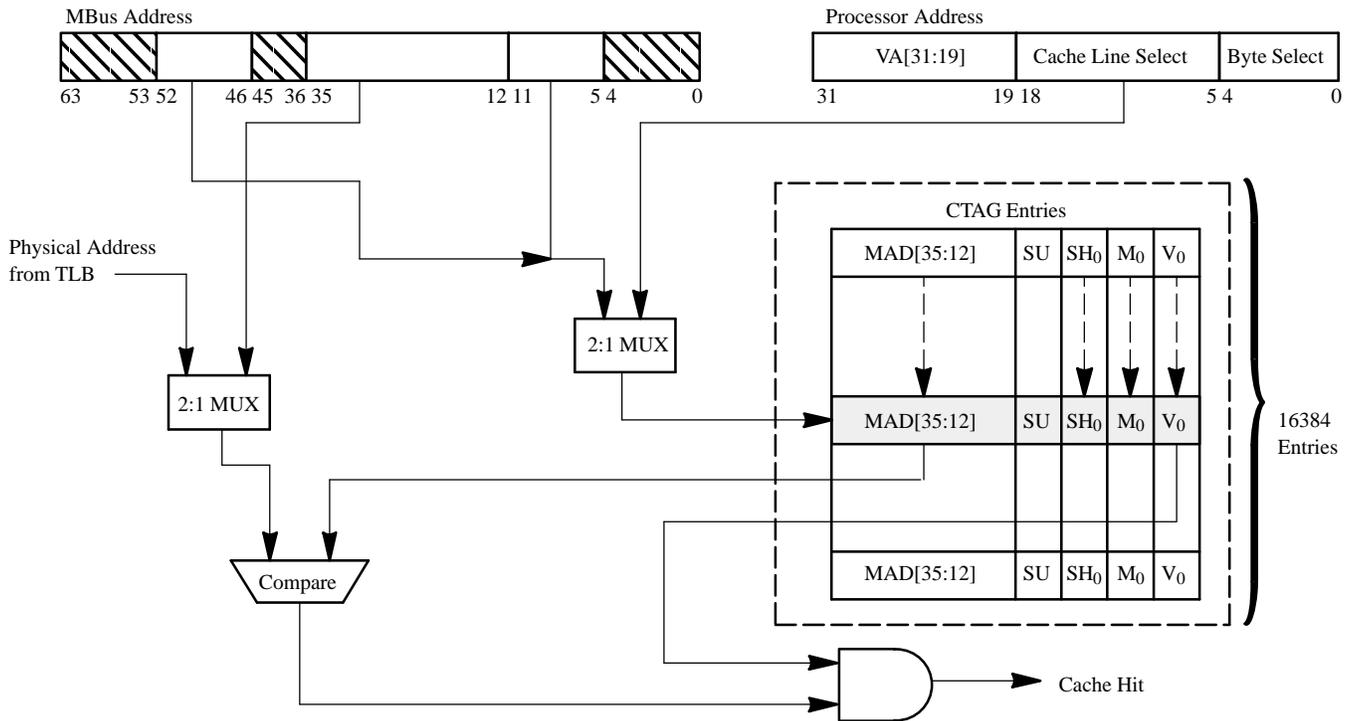


Figure 12. RT626 Cache TAG (CTAG) Comparison (512-Kbyte Cache)

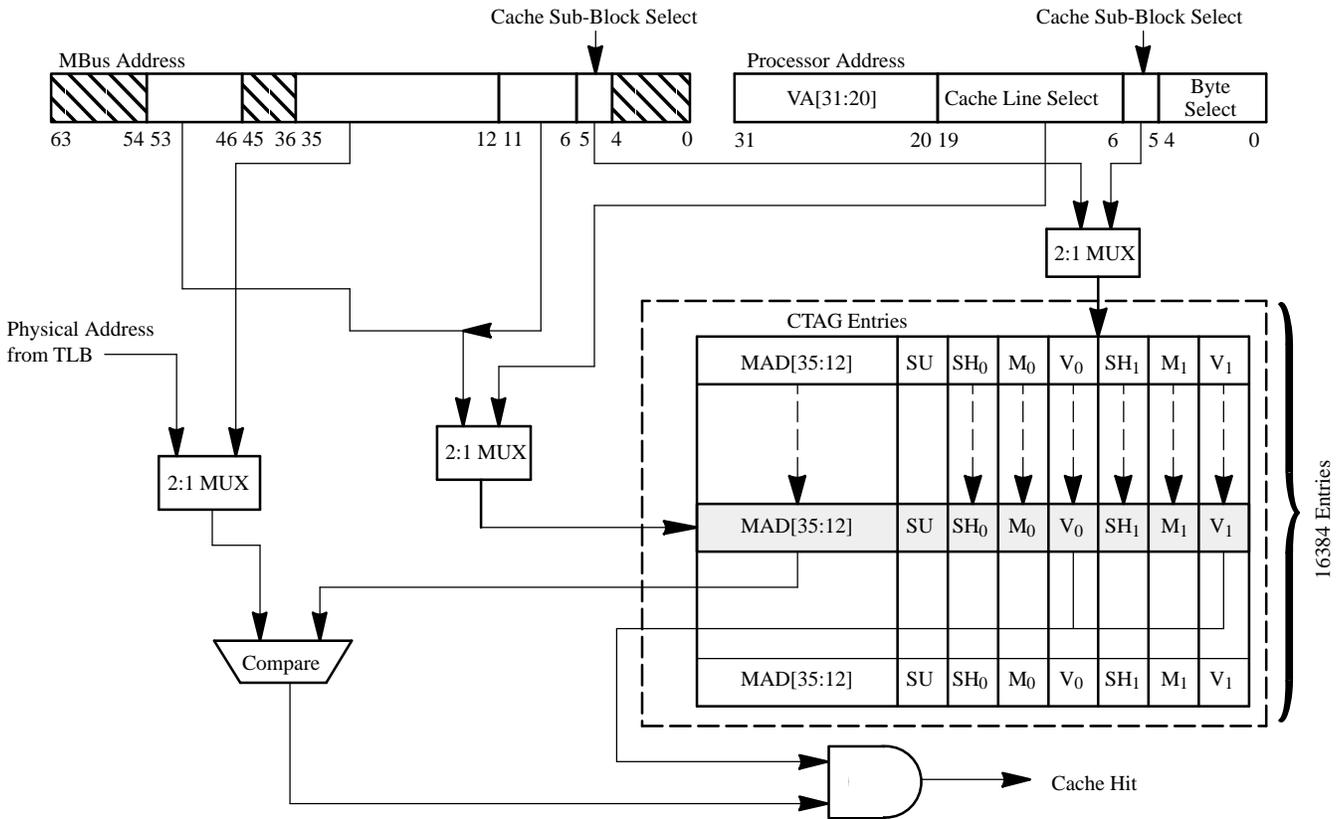


Figure 13. RT626 Cache TAG (CTAG) Comparison (1-Mbyte Cache)

Software Differences

OBP. The Open Boot PROM (OBP) is responsible for determining the size of the cache, setting the *Cache Size* bit in the System Control Register (SCR), and passing cache line size and number of cache lines on to the operating system kernel. The cache size may be hard coded, or it may be determined dynamically by scanning for the largest byte stored using the CACHE DATA ASI (0xF), as shown in the following pseudo-code segment:

```

set (2*1024*1024), %o0 ! 2-Mbyte cache
sta %o0, [%o0]ASI_CACHE_DATA

set (1*1024*1024), %o0 ! 1-Mbyte cache
sta %o0, [%o0]ASI_CACHE_DATA

set (512*1024), %o0 ! 512-Kbyte cache
sta %o0, [%o0]ASI_CACHE_DATA

set (256*1024), %o0 ! 256-Kbyte cache
sta %o0, [%o0]ASI_CACHE_DATA

set (128*1024), %o0 ! 128-Kbyte cache
sta %o0, [%o0]ASI_CACHE_DATA

lda [%g0]ASI_CACHE_DATA, %o1
    
```

The register %o1 will contain the size of the installed cache, since addresses which are larger than the installed cache wrap around to virtual index 0.

When flushing cache lines, a stride of 32-bytes will always work. For 256-Kbyte and 1-Mbyte cache sizes, it is more efficient for software to use a stride of 64-bytes, since both sub-blocks will be flushed. The OBP must use the smallest stride size supported by all CPUs and caches detected in the system.

Cache sizes larger than 256-Kbytes are supported in OBPs available from ROSS (Rev 2.22.1H or later) or SunSoft (Rev 2.25 or later). For more information, contact ROSS Applications Engineering.

Operating System. Generally, no operating system modifications should be necessary due to changes in secondary cache size. Solaris 2.4 and earlier, however, contains a bug which limits operation to systems with cache sizes of 256-Kbytes or less. The bug causes a data area to be overwritten when the cache size exceeds 256-Kbytes. In all standard Solaris 2.4 kernels investigated by Sun, the data area overwritten is not used, so the bug is not evident. It may be possible, however, that a non-standard kernel with a different data layout may experience problems. This bug has been corrected in Solaris 2.5 and later. For more information, contact ROSS Applications Engineering.

Table 4. Cache Tag Entry Address Mapping

512-Kbyte		1-Mbyte	
Address	Cache Tag Entry	Address	Cache Tag Entry
0000x H	0	00000x H	0
0002x H	1	00004x H	1
0004x H	2	00008x H	2
0006x H	3	0000cx H	3
•	•	•	•
•	•	•	•
•	•	•	•
7FFEx H	16383	1FFFCx H	16383

(X = Don't Care)

Appendix C. hyperSPARC Ordering Information

Ordering Code	CPU Clock Frequency (MHz)	Second-level Cache size (per CPU)	MBus Clock Frequency (MHz)
RT6226N-142/1024	142	1M	50
RT6226N-142/1024-66	142	1M	66

For up-to-date ordering and sales information contact:

ROSS Technology, Inc.

5316 Hwy. 290 West
 Austin, Texas 78735-8930 USA
 Telephone: (800) ROSS-YES
 (512) 349-3108
 FAX: (512) 436-2471

ROSS Technology, Inc., Europe

Avenue Ernest Solvay, 80
 1310 La Hulpe
 Belgium
 Telephone: +32 2 652 1014
 FAX: +32 2 652 1062

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